



Material Content Data Sheet



Sales Product Name		ICE5QR0680AZ		Issued		1. August 2018		
MA#		MA001976890						
Package		PG-DIP-7-6		Weight*		651.72 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.325	0.20	0.20	2034	2034
leadframe	inorganic material	phosphorus	7723-14-0	0.049	0.01		75	
	non noble metal	zinc	7440-66-6	0.194	0.03		298	
	non noble metal	iron	7439-89-6	3.884	0.60		5960	
wire	non noble metal	copper	7440-50-8	157.726	24.20	24.84	242015	248348
	noble metal	palladium	7440-05-3	0.001	0.00		2	
	non noble metal	copper	7440-50-8	0.116	0.02	0.02	177	179
encapsulation	organic material	carbon black	1333-86-4	1.438	0.22		2206	
	plastics	epoxy resin	-	46.495	7.13		71342	
	inorganic material	silicondioxide	60676-86-0	431.394	66.20	73.55	661933	735481
leadfinish	non noble metal	tin	7440-31-5	6.460	0.99	0.99	9912	9912
plating	noble metal	silver	7440-22-4	1.911	0.29	0.29	2932	2932
glue	plastics	epoxy resin	-	0.109	0.02		167	
	noble metal	silver	7440-22-4	0.617	0.09	0.11	947	1114
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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